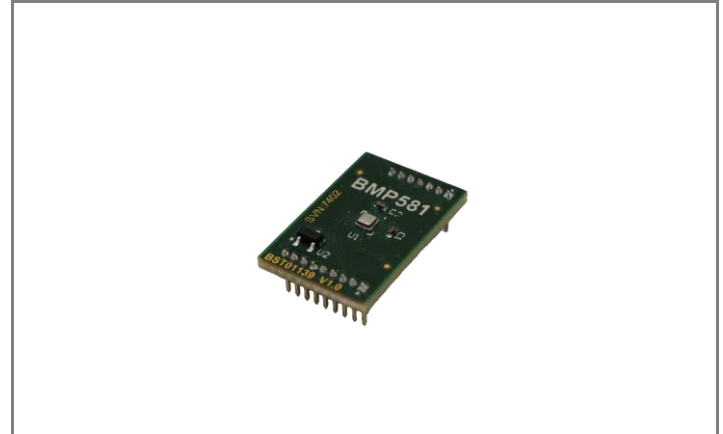


# BMP581

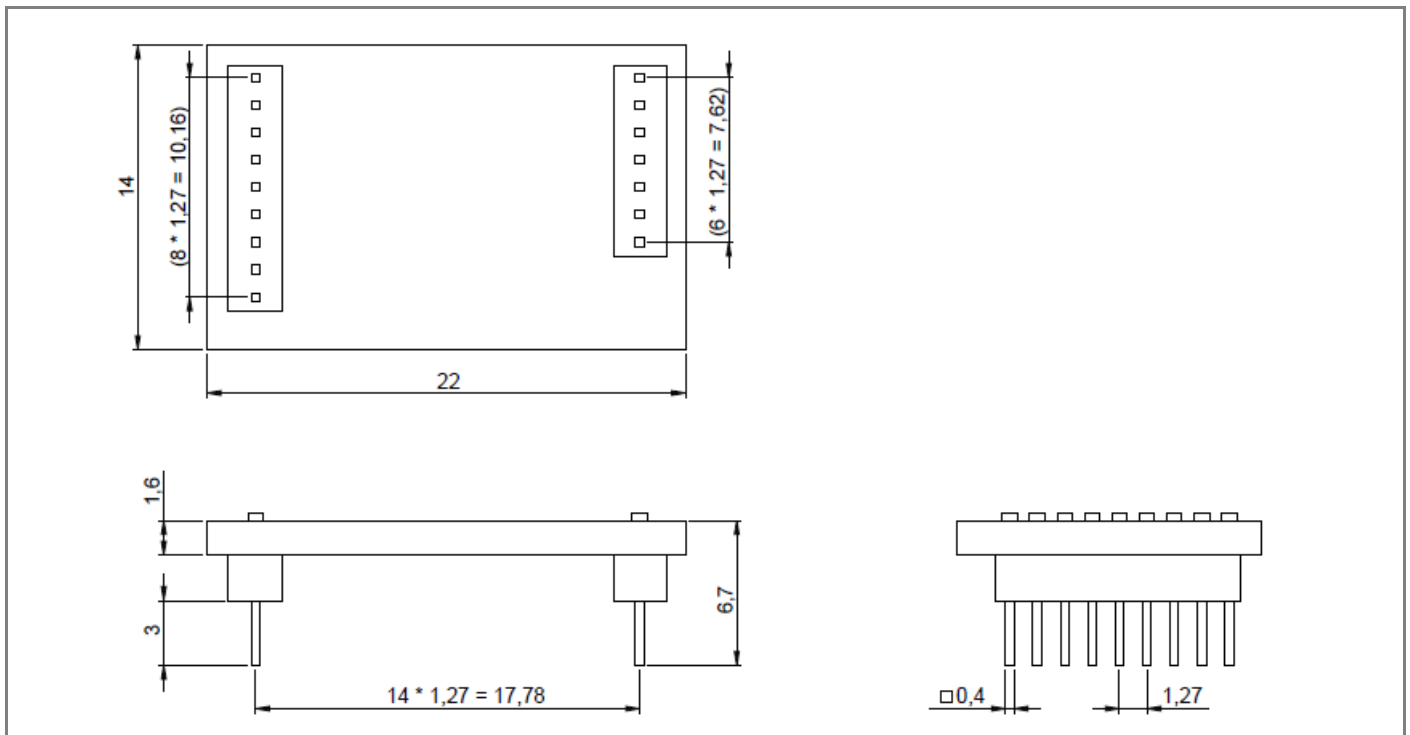
## Shuttle board 3.0 flyer

### GENERAL DESCRIPTION

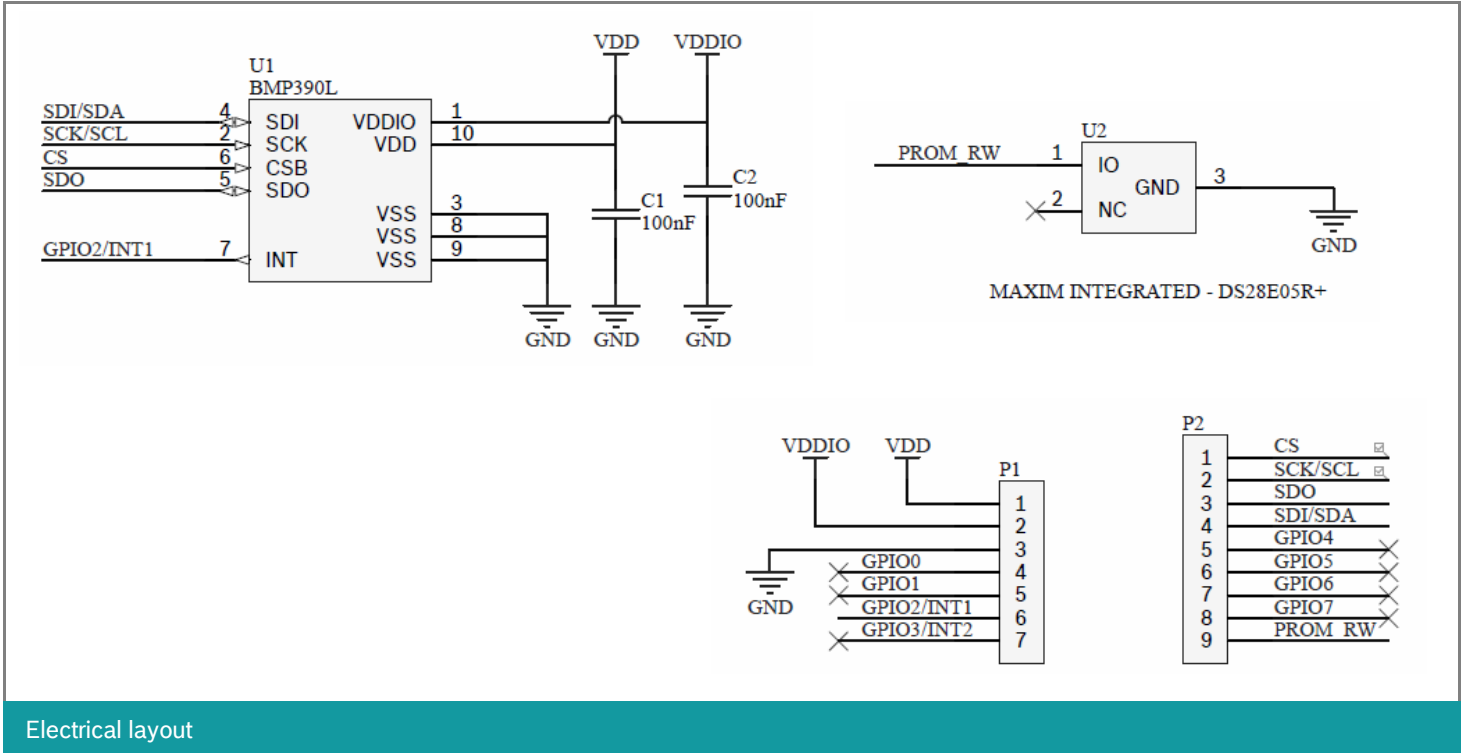
The Bosch Sensortec BMP581 shuttle board 3.0 is a PCB with the pressure and temperature sensor BMP581 mounted on it. In combination with the application board 3.0, the shuttle board can be used to evaluate various functionalities provided on BMP581. The shuttle board allows easy access to the sensor pins via a simple socket and can be directly plugged into the Bosch Sensortec's application board 3.0.



Note: Product photo may differ from real product's appearance



Shuttle board outline dimensions (all dimensions in mm)



Electrical layout

**DESIGNATOR P1 SHUTTLE BOARD CONNECTOR**

Pin	Pin name	Description
1	VDD	Power supply
2	VDDIO	Power supply
3	GND	Ground
4	GPIO0	NC
5	GPIO1	NC
6	GPIO2/INT1	Interrupt pin 1
7	GPIO3/INT2	NC

**DESIGNATOR P2 SHUTTLE BOARD CONNECTOR**

Pin	Pin name	Description
1	CS	Chip selection pin of SPI bus
2	SCK/SCL	Clock pin of both SPI and I2C bus
3	SDO	Master-input-slave-output data pin of SPI bus
4	SDI/SDA	Master-output-slave-input data pin of SPI bus / data pin of I2C bus
5	GPIO4	NC
6	GPIO5	NC
7	GPIO6	NC
8	GPIO7	NC
9	PROM_RW	Connect to EEPROM

Shuttle board identification:

- ▶ Shuttle ID: 0x173
- ▶ Shuttle board identifier: BST01043

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